

In the Claims:

Please cancel Claim 4.

Please amend the claims as follows:

2. (amended) A semiconductor device having an additional conductor network on the chip surface, wherein the power distribution of the integrated circuit is combined with the power distribution of the leadframe, comprising:

- a semiconductor chip having first and second surfaces;

- an integrated circuit fabricated on said first chip surface, said circuit having active components, contact pads, at least one metal layer, and being protected by a mechanically strong, electrically insulating overcoat having a plurality of metal-filled vias to contact said at least one metal layer;

- electrically conductive films deposited on said overcoat and patterned into a network of lines substantially vertically over said active components, said films in contact with said vias and having at least one stress-absorbing film and an outermost film being non-corrodible and metallurgically attachable;

- said network patterned to distribute power current and ground potential;

- a leadframe having a chip mount pad, a first plurality of segments providing electrical signals, and a second plurality of segments providing electrical power and ground;

- said second chip surface attached to said chip mount pad;

- electrical conductors connecting said contact pads with said first plurality of segments; and

- electrical conductors connecting said network lines with said second plurality of segments.

4. (cancelled)

7. (amended) The device according to Claim 2 wherein said leadframe comprises a sheet-like material selected from a group consisting of copper, copper alloy, aluminum, iron-nickel alloy, or invar.

10. (amended) The device according to Claim 8 wherein leadframe segment portions not included in said encapsulation are shaped as leads solderable to outside parts.

11. (amended) The device according to Claim 2 further comprising solder balls attached to said electrical conductors connecting said network lines with said second plurality of segments.

12. (amended) The device according to Claim 2 further comprising a wire bond to said electrical conductors connecting said network lines with said second plurality of segments.

15. (amended) The device according to Claim 2 wherein said conductors are bonding wires or solder balls.

REMARKS

Reconsideration of the above-referenced application in view of the following remarks is respectfully requested.

Claims 1-23 were pending in this application. Claims 20-23 have been withdrawn from consideration. Claim 4 has been cancelled. Claims 2, 7, 10, 11, 12, and 15 have been amended to better define the scope of the claimed invention.